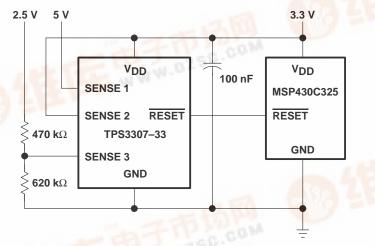
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- Triple Supervisory Circuits for DSP and Processor-Based Systems
- Power-On Reset Generator with Fixed Delay Time of 200 ms, No External Capacitor Needed
- Temperature-Compensated Voltage Reference
- Maximum Supply Current of 40 μA
- Supply Voltage Range . . . 2 V to 6 V
- Defined RESET Output from V<sub>DD</sub> ≥ 1.1 V
- MSOP-8 and SO-8 Packages
- Temperature Range . . . 40°C to 85°C

# SENSE1 1 8 VDD SENSE2 2 7 MR SENSE3 3 6 RESET GND 4 5 RESET

# typical applications

Figure 1 lists some of the typical applications for the TPS3307 family, and a schematic diagram for a processor-based system application. This application uses TI part numbers TPS3307–33 and MSP430C325.



- Applications using DSPs, Microcontrollers or Microprocessors
- Industrial Equipment
- Programmable Controls
- Automotive Systems
- Portable/Battery Powered Equipment
- Intelligent Instruments
- Wireless Communication Systems
- Notebook/Desktop Computers

Figure 1. Applications Using the TPS3307 Family

### description

The TPS3307 family is a series of micropower supply voltage supervisors designed for circuit initialization primarily in DSP and processor-based systems, which require more than one supply voltage.

The product spectrum of the TPS3307-xx is designed for monitoring three independent supply voltages: 3.3 V/1.8 V/adj, 3.3 V/2.5 V/adj or 3.3 V/5 V/adj. The adjustable SENSE input allows the monitoring of any supply voltage >1.25 V.

The various supply voltage supervisors are designed to monitor the nominal supply voltage as shown in the following supply voltage monitoring table.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



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### description (continued)

#### SUPPLY VOLTAGE MONITORING

DEVICE	NOMINAL SUPERVISED VOLTAGE			THRESHOLD VOLTAGE (TYP)		
DEVICE	SENSE1	SENSE2	SENSE3	SENSE1	SENSE2	SENSE3
TPS3307-18	3.3 V	1.8 V	User defined	2.93 V	1.68 V	1.25 V <sup>†</sup>
TPS3307-25	3.3 V	2.5 V	User defined	2.93 V	2.25 V	1.25 V <sup>†</sup>
TPS3307-33	5 V	3.3 V	User defined	4.55 V	2.93 V	1.25 V <sup>†</sup>

<sup>†</sup>The actual sense voltage has to be adjusted by an external resistor divider according to the application requirements.

During power-on,  $\overline{RESET}$  is asserted when the supply voltage  $V_{DD}$  becomes higher than 1.1 V. Thereafter, the supply voltage supervisor monitors the SENSEn inputs and keeps  $\overline{RESET}$  active as long as SENSEn remain below the threshold voltage  $V_{IT+}$ .

An internal timer delays the return of the  $\overline{RESET}$  output to the inactive state (high) to ensure proper system reset. The delay time,  $t_{d\,typ}$  = 200 ms, starts after all SENSEn inputs have risen above the threshold voltage  $V_{IT+}$ . When the voltage at any SENSE input drops below the threshold voltage  $V_{IT-}$ , the  $\overline{RESET}$  output becomes active (low) again.

The TPS3307-xx family of devices incorporates a manual reset input,  $\overline{\text{MR}}$ . A low level at  $\overline{\text{MR}}$  causes  $\overline{\text{RESET}}$  to become active. In addition to the active-low  $\overline{\text{RESET}}$  output, the TPS3307-xx family includes an active-high RESET output.

The devices are available in either 8-pin MSOP or standard 8-pin SO packages.

The TPS3307-xx devices are characterized for operation over a temperature range of – 40°C to 85°C.

### **AVAILABLE OPTIONS**

	PACKAGEI	DEVICES			
TA	SMALL OUTLINE (D)	PowerPAD™ μ-SMALL OUTLINE (DGN)	MARKING DGN PACKAGE	CHIP FORM (Y)	
	TPS3307-18D	TPS3307-18DGN	TIAAP	TPS3307-18Y	
–40°C to 85°C	TPS3307-25D	TPS3307-25DGN	TIAAQ	TPS3307-25Y	
	TPS3307-33D	TPS3307-33DGN	TIAAR	TPS3307-33Y	

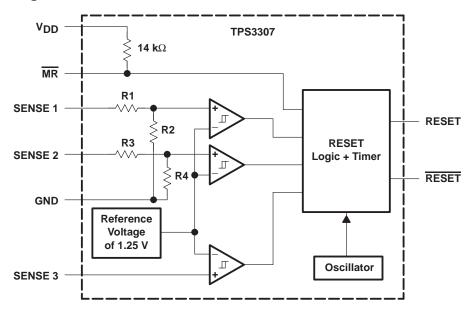
### **FUNCTION/TRUTH TABLES**

MR	SENSE1>VIT1	SENSE2>V <sub>IT2</sub>	SENSE3>VIT3	RESET	RESET
L	χ†	χ†	X	L	Н
Н	0	0	0	L	н
Н	0	0	1	L	Н
Н	0	1	0	L	Н
Н	0	1	1	L	Н
Н	1	0	0	L	Н
Н	1	0	1	L	Н
Н	1	1	0	L	Н
Н	1	1	1	Н	L

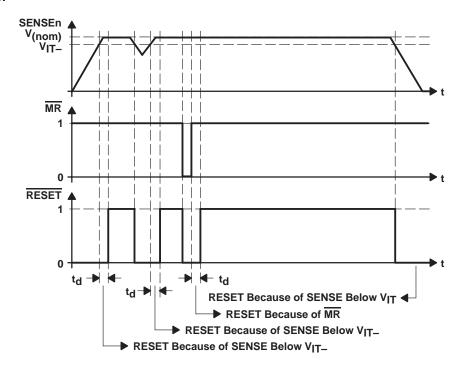
<sup>†</sup> X = Don't care



# functional block diagram



# timing diagram

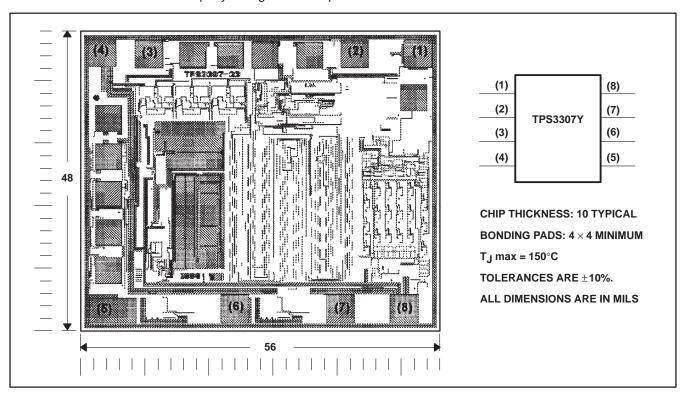




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### **TPS3307Y** chip information

These chips, when properly assembled, display characteristics similar to those of the TPS3307. Thermal compression or ultrasonic bonding may take place on the doped aluminium bonding pads. The chips may be mounted with conductive epoxy or a gold-silicon preform.



### **Terminal Functions**

TERMIN	AL	1/0	DESCRIPTION
NAME	NO.	1/0	DESCRIPTION
GND	4		Ground
MR	7	- 1	Manual reset
RESET	5	0	Active-low reset output
RESET	6	0	Active-high reset output
SENSE1	1	1	Sense voltage input 1
SENSE2	2		Sense voltage input 2
SENSE3	3	I	Sense voltage input 3
$V_{DD}$	8		Supply voltage



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# absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V <sub>DD</sub> (see Note1)	7 V
All other pins (see Note 1)	
Maximum low output current, I <sub>OL</sub>	5 mA
Maximum high output current, IOH	–5 mA
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{DD}$ )	±20 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ or $V_O > V_{DD}$ )	±20 mA
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T <sub>A</sub>	40°C to 85°C
Storage temperature range, T <sub>stq</sub>	65°C to 150°C
Soldering temperature	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to GND. For reliable operation the device must not be operated at 7 V for more than t = 1000 h continuously.

#### **DISSIPATION RATING TABLE**

PACKAGE	$T_{\mbox{$\Delta$}} \leq 25^{\circ}\mbox{$C$}$ POWER RATING	A		T <sub>A</sub> = 85°C POWER RATING	
DGN	2.14 mW	17.1 mW/°C	1.37 mW	1.11 mW	
D	725 mW	5.8 mW/°C	464 mW	377 mW	

### recommended operating conditions at specified temperature range

	MIN	MAX	UNIT
Supply voltage, V <sub>DD</sub>	2	6	V
Input voltage at MR and SENSE3, VI	0	V <sub>DD</sub> +0.3	V
Input voltage at SENSE1 and SENSE2, V <sub>I</sub>	0	(V <sub>DD</sub> +0.3)V <sub>IT</sub> /1.25V	V
High-level input voltage at MR, VIH	0.7xV <sub>DD</sub>		V
Low-level input voltage at MR, V <sub>IL</sub>		0.3×V <sub>DD</sub>	V
Input transition rise and fall rate at $\overline{MR}$ , $\Delta t/\Delta V$		50	ns/V
Operating free-air temperature range, TA	-40	85	°C



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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER		TEST CON	DITIONS	MIN	TYP	MAX	UNIT	
			$V_{DD} = 2 \text{ V to 6 V},$	I <sub>OH</sub> = -20 μA	V <sub>DD</sub> - 0.2V				
Vон	High-level output voltage		$V_{DD} = 3.3 \text{ V},$	$I_{OH} = -2 \text{ mA}$	V <sub>DD</sub> - 0.4V			V	
			$V_{DD} = 6 V$ ,	$I_{OH} = -3 \text{ mA}$	V <sub>DD</sub> - 0.4V				
			$V_{DD} = 2 V \text{ to } 6 V$	I <sub>OL</sub> = 20 μA			0.2		
VOL	Low-level output voltage		$V_{DD} = 3.3 V,$	$I_{OL} = 2 \text{ mA}$			0.4	V	
			V <sub>DD</sub> = 6 V,	$I_{OL} = 3 \text{ mA}$			0.4		
	Power-up reset voltage (see Note 2)		V <sub>DD</sub> ≥ 1.1 V,	$I_{OL} = 20 \mu A$			0.4	V	
		VSENSE3	$V_{DD} = 2 \text{ V to 6 V},$ $T_{A} = 0^{\circ}\text{C to 85}^{\circ}\text{C}$		1.22	1.25	1.28		
			1		1.64	1.68	1.72	.,	
V <sub>IT</sub> —		VSENSE1,			2.20	2.25	2.30	V	
		VSENSE2			2.86	2.93	3		
	Negative-going input threshold voltage (see Note 3)				4.46	4.55	4.64		
		VSENSE3	$V_{DD} = 2 \text{ V to 6 V},$ $T_{A} = -40^{\circ}\text{C to }85^{\circ}$	С	1.22	1.25	1.29	V	
			1		1.64	1.68	1.73		
		VSENSE1,			2.20	2.25	2.32	2.32 3.02	
		VSENSE2			2.86	2.93	3.02		
					4.46	4.55	4.67		
			V <sub>IT</sub> _ = 1.25 V			10			
			V <sub>IT</sub> _ = 1.68 V			15			
V <sub>hys</sub>	Hysteresis at VSENSEn input		V <sub>IT</sub> _ = 2.25 V			20		mV	
			V <sub>IT</sub> _ = 2.93 V			30			
			V <sub>IT</sub> _ = 4.55 V			40			
		MR	$\overline{MR} = 0.7 \times V_{DD}$	V <sub>DD</sub> = 6 V		-130	-180		
l <sub>IH</sub>	High-level input current	SENSE1	VSENSE1 = V <sub>DD</sub> :	= 6 V		5	8	μΑ	
' <sup></sup>	riigir level input current	SENSE2	VSENSE2 = V <sub>DD</sub> :	= 6 V		6	9	μΛ	
		SENSE3	VSENSE3 = V <sub>DD</sub>		-1		1		
   <sub> </sub>  _	Low-level input current	MR	$\overline{MR} = 0 \text{ V},$	$V_{DD} = 6 V$		-430	-600	00 μΑ	
<u>'</u>		SENSEn	VSENSE1,2,3 = 0	V	-1		1	μι	
IDD	Supply current						40	μΑ	
Ci	Input capacitance		$V_I = 0 V \text{ to } V_{DD}$			10		pF	

NOTES: 2. The lowest supply voltage at which  $\overline{\text{RESET}}$  becomes active.  $t_r$ ,  $V_{DD} \ge 15 \,\mu\text{s/V}$ 



<sup>3.</sup> To ensure best stability of the threshold voltage, a bypass capacitor (ceramic  $0.1\,\mu\text{F}$ ) should be placed close to the supply terminals.

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# timing requirements at $\rm V_{DD}$ = 2 V to 6 V, $\rm R_{L}$ = 1 M $\Omega,\, C_{L}$ = 50 pF, $\rm T_{A}$ = 25 $^{\circ}C$

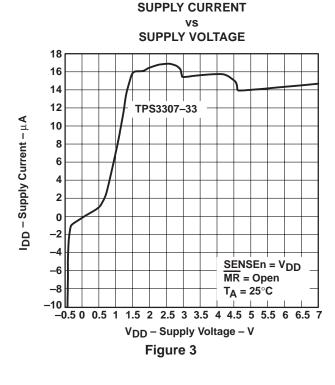
PARAMETER			TEST CONDITIONS			TYP	MAX	UNIT
4 Duda a suialth	SENSEn	VSENSEnL = VIT0.2 V,	VSENSEnH = VIT+ +0.2 V	6			μs	
ıw.	Pulse width	MR	$V_{IH} = 0.7 \times V_{DD}$	$V_{IL} = 0.3 \times V_{DD}$	100			ns

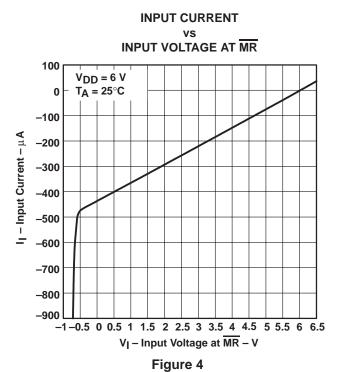
# switching characteristics at V\_DD = 2 V to 6 V, R $_L$ = 1 M $\Omega$ , C $_L$ = 50 pF, T $_A$ = 25 $^{\circ}$ C

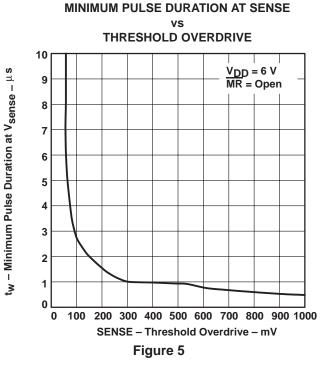
	PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t <sub>d</sub>			$\frac{VI(SENSEn)}{MR} \ge V_{IT+} + 0.2 \text{ V},$ $\frac{VI(SENSEn)}{MR} \ge 0.7 \times V_{DD}, \text{ See timing diagram}$	140	200	280	ms
tPHL	Propagation (delay) time, high-to-low level output	MR to RESET MR to RESET	V <sub>I</sub> (SENSEn) ≥ V <sub>IT+</sub> +0.2 V,		200	500	ns
<sup>t</sup> PLH	Propagation (delay) time, low-to-high level output	MR to RESET MR to RESET	$V_{IH} = 0.7 \times V_{DD},  V_{IL} = 0.3 \times V_{DD}$		200	300	113
<sup>t</sup> PHL	Propagation (delay) time, high-to-low level output	SENSEn to RESET SENSEn to RESET	V <sub>IH</sub> = V <sub>IT+</sub> +0.2 V, V <sub>IL</sub> = V <sub>IT-</sub> -0.2 V,		1	5	
<sup>t</sup> PLH	Propagation (delay) time, low-to-high level output	SENSEn to RESET SENSEn to RESET	$\overline{MR} \ge 0.7 \times V_{DD}$		'	5	μs

### TYPICAL CHARACTERISTICS

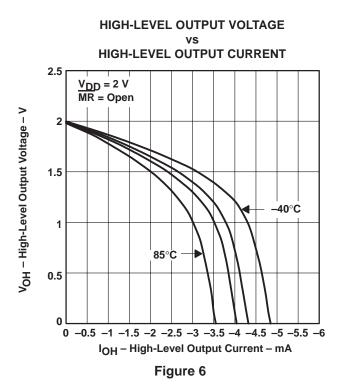
# NORMALIZED SENSE THRESHOLD VOLTAGE FREE-AIR TEMPERATURE AT VDD Normalized Input Threshold Voltage – VIT(TA), VIT(25 °C) 1.005 **V<sub>DD</sub>** = 2 V 1.004 MR = Open 1.003 1.002 1.001 0.999 0.998 0.997 0.996 0.995 85 -40 10 T<sub>A</sub> - Free-Air Temperature - °C Figure 2







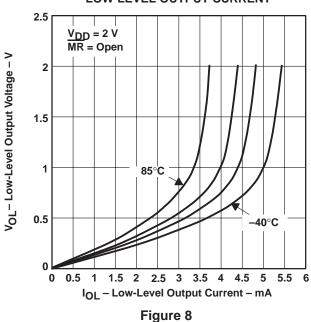
### TYPICAL CHARACTERISTICS



LOW-LEVEL OUTPUT VOLTAGE

vs

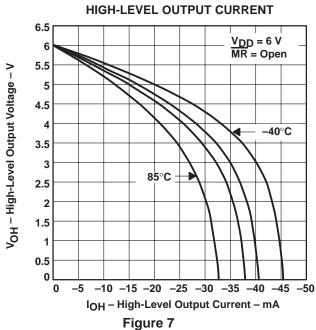
LOW-LEVEL OUTPUT CURRENT



HIGH-LEVEL OUTPUT VOLTAGE

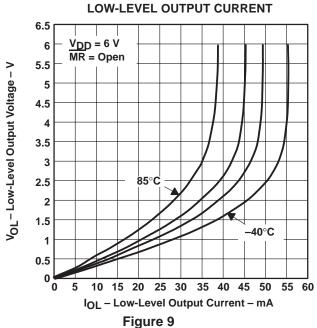
vs

HIGH-LEVEL OUTPUT CURRENT



LOW-LEVEL OUTPUT VOLTAGE

VS
LOW-LEVEL OUTPUT CURRENT



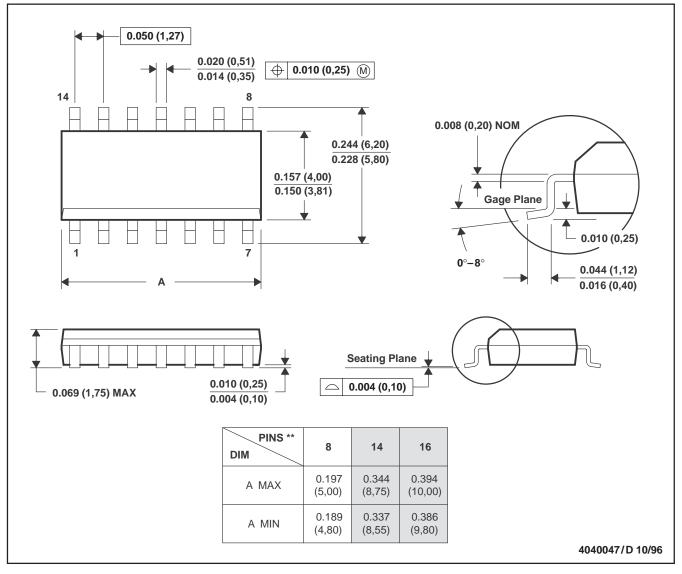
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### **MECHANICAL DATA**

### D (R-PDSO-G\*\*)

### 14 PIN SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012

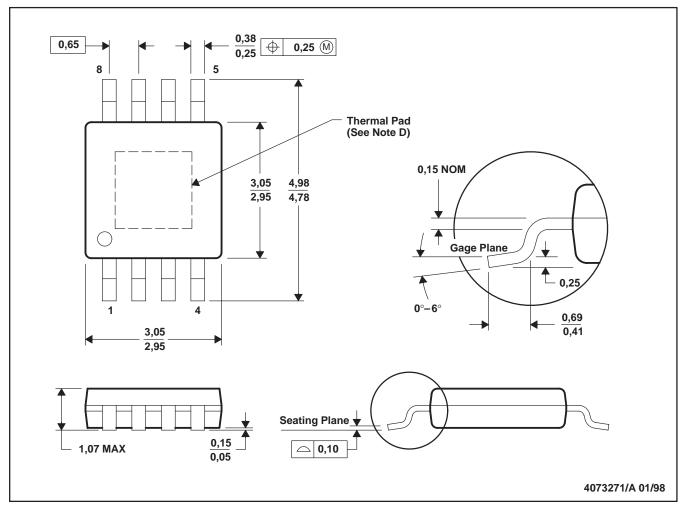


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### **MECHANICAL DATA**

# **DGN (S-PDSO-G8)**

### PowerPAD™ PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions include mold flash or protrusions.
- D. The package thermal performance may be enhanced by attaching an external heat sink to the thermal pad. This pad is electrically and thermally connected to the backside of the die and possibly selected leads.
- E. Falls within JEDEC MO-187



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